

IN THE CLAIMS

Claims 1-2 (Cancelled).

Claim 3 (Previously Presented): The synthetic resin molded material according to Claim 11, wherein said thin film is a film comprising SiO_2 as the main component.

Claim 4 (Previously Presented): The synthetic resin molded material according to Claim 11, wherein said thin film is a thin film comprising oxides of Si and Sn as the main components.

Claim 5 (Previously Presented): The synthetic resin molded material according to Claim 11, wherein said thin film is a thin film comprising oxides of Si and Ti as the main components.

Claim 6 (Previously Presented): The synthetic resin molded material according to Claim 11, wherein said thin film is a thin film comprising oxides of Si, Sn and Ti as the main components.

Claims 7-8 (Cancelled).

Claim 9 (Previously Presented): The synthetic resin molded material according to Claim 11, wherein said synthetic resin molded material is a covering material for an agricultural or horticultural house.

Claim 10 (Cancelled).

Claim 11 (Previously Presented): A synthetic resin molded material comprising a thin film made of a mixture of Si oxide and an oxide of at least one metal selected from the group consisting of Zr, Ti, Ta, Nb, Sn, and Zn, formed by a sputtering method on a synthetic resin substrate having hydrophobicity,

wherein said thin film has a thickness of up to 100 nm;

wherein said synthetic resin substrate is a tetrafluoroethylene type resin; and

wherein the Si content is from 50 to 80 atomic % of the total metals.

Claim 12 (Previously Presented): A method for producing a synthetic resin molded material comprising a thin film made of a mixture of Si oxide and an oxide of at least one metal selected from the group consisting of Zr, Ti, Ta, Nb, Sn and Zn, wherein said film is formed by a sputtering method on a tetrafluoroethylene type resin substrate having hydrophobicity, wherein said thin film has a thickness of up to 100 nm.

Claim 13 (Previously Presented): The synthetic resin molded material according to Claim 11, wherein said tetrafluoroethylene type resin is a tetrafluoroethylene/ethylene copolymer.

Claim 14 (Previously Presented): The method according to Claim 12, wherein said tetrafluoroethylene type resin substrate is a tetrafluoroethylene/ethylene copolymer substrate.

Claim 15 (New): The synthetic resin molded material according to Claim 11, wherein said thin film has a thickness of from 3 to 30 nm.

Claim 16 (New): The synthetic resin molded material according to Claim 11, wherein the silica content is from 50 to 70 atomic % of the total metals.

Claim 17 (New): The synthetic resin molded material according to Claim 13, wherein the tetrafluoroethylene/ethylene copolymer comprises tetrafluoroethylene/ethylene in a molar ratio of 40/60 to 70/30, and optionally comprises additionally from 0.3 to 10 mol% of comonomer components other than tetrafluoroethylene and ethylene.

Claim 18 (New): The method according to Claim 14, wherein the tetrafluoroethylene/ethylene copolymer comprises tetrafluoroethylene/ethylene in a molar ratio of 40/60 to 70/30, and optionally comprises additionally from 0.3 to 10 mol% of comonomer components other than tetrafluoroethylene and ethylene.

DISCUSSION OF THE AMENDMENT

New Claims 15-18 have been added. Claim 15 is supported in the specification at page 5, lines 1-5; Claim 16 is supported at page 6, lines 3-5; and Claims 17 and 18 are supported at page 11, lines 13-17.

No new matter has been added by the above amendment. Claims 3-6, 9, and 11-18 are now pending in the application.